1. Record Nr. UNINA9910404075003321

| | |
|---|---|
| Autore | Beyes Timon |
| Titolo | Organize / / Timon Beyes [and four others] |
| Pubbl/distr/stampa | Mannheim : , : Meson press, , 2019 |
| Descrizione fisica | 1 online resource (103 pages) |
| Collana | In Search of Media |
| Disciplina | 302.23 |
| Soggetti | Mass media - Social aspects |
| Lingua di pubblicazione | Inglese |
| Formato | Materiale a stampa |
| Livello bibliografico | Monografia |
| Nota di contenuto | Series Foreword vii -- Introduction ix -- Timon Beyes, Lisa Conrad, and Reinhoid Martin -- [ 1 ] Media Organize: Persons Reinhoid Martin 1 -- [ 2 ] Organizing Media: Security and Entertainment Timon Beyes 29 -- [ 3 ] Organization Is the Message: Gray Media Lisa Conrad 63 -- Afterword: Propositions on the Organizational Form Geert Lovink and Ned Rossiter 89 -- Authors 102. |
| Sommario/riassunto | Digital media technologies re-pose the question of organization - and thus of power and domination, control and surveillance, disruption and emancipation. This book interrogates organization as effect and condition of media. How can we understand the recursive relationship between media and organization? How can we think, explore, critique - and perhaps alter - the organizational bodies and scripts that shape contemporary life?. |

2. Record Nr. UNINA9910830592903321

| | |
|---|---|
| Autore | Kao Imin |
| Titolo | Wafer manufacturing : shaping of single crystal silicon wafers / / Imin Kao, Chunhui Chung |
| Pubbl/distr/stampa | Hoboken, New Jersey : , : John Wiley & Sons, Incorporated, , [2021]<br>Â©2021 |
| ISBN | 1-118-69625-5<br>1-118-69623-9<br>1-118-69622-0 |
| Edizione | [First edition.] |
| Descrizione fisica | 1 online resource (307 pages) : illustrations |
| Disciplina | 621.38152 |
| Soggetti | Semiconductor wafers - Design and construction |
| Lingua di pubblicazione | Inglese |
| Formato | Materiale a stampa |
| Livello bibliografico | Monografia |
| Note generali | Includes index. |
| Sommario/riassunto | "A wafer (often from silicon crystals) is a thin slice of semiconducting material, upon which microcircuits are constructed by doping, etching, and deposition of various materials. Generally, they are cut from a semiconductor using a diamond saw, then polished on one or both faces. Wafer slicing is the first post crystal-growth step toward producing a polished wafer for electronic device fabrication in the semiconductor and photovoltaic (PV) industry. Advanced slicing technologies such as wiresawing are nowadays widely used in wafer production because of its ability to cut single crystalline and polycrystalline crystals with large diameter and produce wafers from thick (a few mm) to very thin sizes (300 microns)."-- |